

MIL-STD-1553B Notice 2 ADVANCED Integrated MUX Hybrids with Enhanced RT Features (AIM-HY'er)

DESCRIPTION

DDC's BUS-61559 series of Advanced Integrated Mux Hybrids with enhanced RT Features (AIM-HY'er) comprise a complete interface between a microprocessor and a MIL-STD-1553B Notice 2 bus, implementing Bus Controller (BC), Remote Terminal (RX), and Monitor Terminal (MT) modes. Packaged in a single 78-pin DIP or 82-pin flat package the BUS-61559 series contains dual low-power transceivers and encoder/decoders, complete BC/RT/MT protocol logic, memory management and interrupt logic, 8K x 16 of shared static RAM, and a direct, buffered interface to a host processor bus.

The BUS-61559 includes a number of advanced features in support of MIL-STD-1553B Notice 2 and STANAG 3838. Other salient features of the BUS-61559 serve to provide the benefits of reduced board space requirements enhanced software flexibility, and reduced host processor overhead

The BUS-61559 contains internal address latches and bidirectional data

buffers to provide a direct interface to a host processor bus. Alternatively, the buffers may be operated in a fully transparent mode in order to interface to up to 64K words of external shared RAM and/or connect directly to a component set supporting the 20 MHz STANAG-3910 bus.

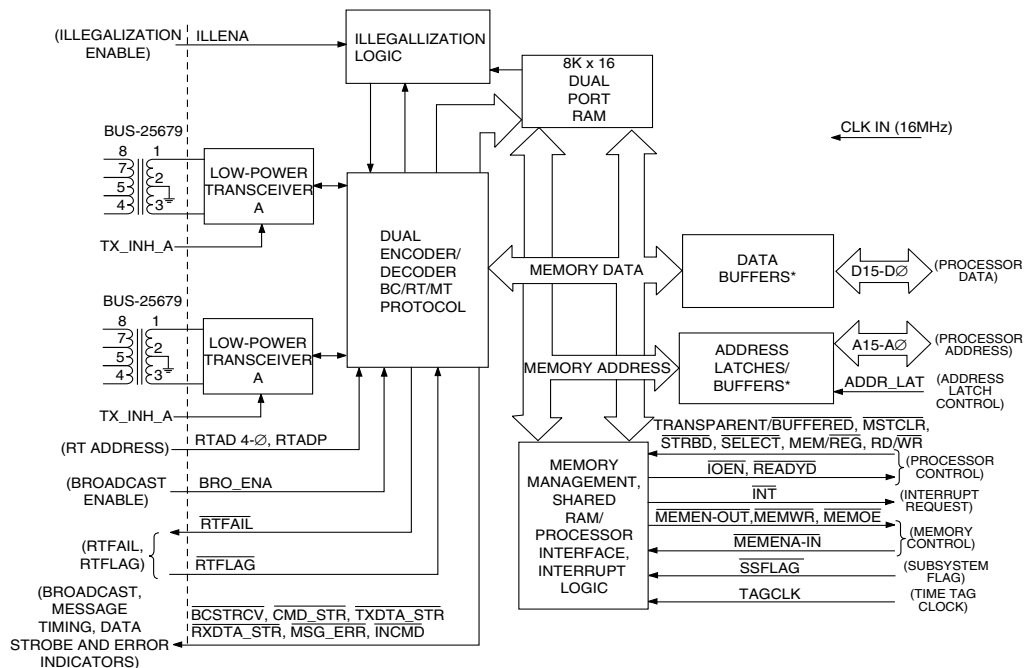
The memory management scheme for RT mode prevails an option for separation of broadcast data, in compliance with 1553B Notice 2. A circular buffer option for RT message data blocks offloads the host processor for bulk data transfer applications.

Another feature besides those listed to the right, is a transmitter inhibit control for the individual bus channels.

The BUS-61559 series hybrids operate over the full military temperature range of -55 to +125°C and MIL-PRF-38534 processing is available. The hybrids are ideal for demanding military and industrial microprocessor-to-1553 applications

FEATURES

- Complete Integrated 1553B Notice 2 Interface Terminal
- Functional Superset of BUS-61553 AIM-HYSeries
- Internal Address and Data Buffers for Direct Interface to Processor Bus
- RT Subaddress Circular Buffers to Support Bulk Data Transfers
- Optional Separation of RT Broadcast Data
- Internal Interrupt Status and Time Tag Registers
- Internal ST Command Illegalization
- MIL-PRF-38534 Processing Available



BU-61559 BLOCK DIAGRAM

ORDERING INFORMATION

BUS-615XX-XX0X*

Supplemental Process Requirements:

- S = Pre-Cap Source Inspection
- L = Pull Test
- Q = Pull Test and Pre-Cap Inspection
- K = One Lot Date Code
- W = One Lot Date Code and PreCap Source
- Y = One Lot Date Code and 100% Pull Test
- Z = One Lot Date Code, PreCap Source and 100% Pull Test
- Blank = None of the Above

Process Requirements:

- 0 = Standard DDC Processing, no Burn-In (See page xiii.)
- 1 = MIL-PRF-38534 Compliant
- 2 = B**
- 3 = MIL-PRF-38534 Compliant with PIND Testing
- 4 = MIL-PRF-38534 Compliant with Solder Dip
- 5 = MIL-PRF-38534 Compliant with PIND Testing and Solder Dip
- 6 = B** with PIND Testing
- 7 = B** with Solder Dip
- 8 = B** with PIND Testing and Solder Dip
- 9 = Standard DDC Processing with Solder Dip, no Burn-In (See page xiii.)

Temperature Grade/Data Requirements:

- 1 = -55°C to +125°C
- 2 = -40°C to +85°C
- 3 = 0°C to +70°C
- 4 = -55°C to +125°C with Variables Test Data
- 5 = -40°C to +85°C with Variables Test Data
- 8 = 0°C to +70°C with Variables Test Data

Power Supply and Packaging

- 59 = +5 V/-15 V DDIP
- 60 = +5 V/-12 V DIP
- 69 = +5 V/-15 V Flat Pack
- 70 = +5 V/-12 V Flat Pack
- 71 = +5 V Flat Pack

*-601 version also available = MIL-STD-1760 compatible with fully compliant MIL-PRF-38534 Processing Available

These products contain tin-lead solder finish as applicable to solder dip requirements.

STANDARD DDC PROCESSING FOR HYBRID AND MONOLITHIC HERMETIC PRODUCTS		
TEST	MIL-STD-883	
	METHOD(S)	CONDITION(S)
INSPECTION	2009, 2010, 2017, and 2032	—
SEAL	1014	A and C
TEMPERATURE CYCLE	1010	C
CONSTANT ACCELERATION	2001	3000g
BURN-IN	1015 ^(Note 1) 1030 ^(Note 2)	TABLE 1

Notes:

1. For Process Requirement "B"* (refer to ordering information), devices may be non-compliant with MIL-STD-883, Test Method 1015, Paragraph 3.2. Contact factory for details.
2. When applicable.

NOTES

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Please visit our web site at www.ddc-web.com for the latest information.



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